## Atty Docket: **FORM PTO-1449** 01-446 Serial #: INFORMATION DISCLOSURE CITATIONS Zhu, Wang Applicant: IN AN APPLICATION Filing Date: 2001.09.28 Group: **U.S. PATENT DOCUMENTS** Name Class Sub-Class Cite# Date Filing Date **Document Number** Examiner Initial

## **FOREIGN PATENT DOCUMENTS**

Exam	niner	Cite#	Document Number	Date	Country	Class	Sub-Class	Translation
Init	ial							

## **OTHER NON-PATENT DOCUMENTS**

Examiner	Cite#	Author, title, date, pertinent pages, etc.		
Initial				
	1	S. Gandikota, et al., "Extension of Copper Plating to 0.13 micron Nodes by Rulse-Modulated Plating," Proceedings of		
		The International Interconnect Technology Conference, California, June 2000.)		

Examiner Date Considered: Date Considered: EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Instude copy of this form with next communication to Applicant.

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